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Note: MVME130, VMX32bus and MVME224 are all Trademarks of Motorola Inc.

SECTION I

GENERAL INFORMATION

1.1 INTRODUCTION

This manual describes the elements of operation and installation procedures of the **MM6260D High Speed VMEbus Dynamic Random Access Memory Module**.

1.2 GENERAL DESCRIPTION

The **MM6260D High Speed Memory** is compatible with the **VMEbus C.1** specification. Inherent to the module are **VMEbus** options D32, D16 & D8 (32, 16 & 8 bit data path width), and A32, A24 (32, 24 bit address path width). The module also generates and stores a parity bit for each byte memory location on write cycles and checks this bit for each byte location read on read cycles. If a parity error is detected on a read access, the module sets a Control Status Register (**CSR**) bit, and may be programmed to assert the bus error signal.

For Extremely High Performance operation, the **MM6260D High Speed Memory** is equipped with a **High Speed BLOCK Mode Transfer** capability. This allows the use of **High Performance Block Mode Controllers** to transfer up to 256 bytes on the **VMEbus**, using standard VME block transfer address modifiers; or to transfer up to 256 Kbytes (\$40000) using special (user definable) address modifiers.

While the **MM6260D High Speed Memory** was designed as a 32 bit wide (data path) memory board, and complies with **VMEbus Specifications (Revision C.1)** it can be addressed as 8 bit bytes, 16 bit words, 16 bit or 24 bit unaligned transfers or 32 bit longwords. The **MM6260D Memory** can be configured for 8M, 12M, and 16M bytes capacity by populating it with industry standard 1 Megabit CMOS DRAM Zig Zag Packages (ZIP). Additional capacity of 24M, 28M and 32M bytes may be obtained by adding a **MM6262** mezzanine board, which is populated with industry standard 1 Megabit CMOS DRAM in SOJ packages.

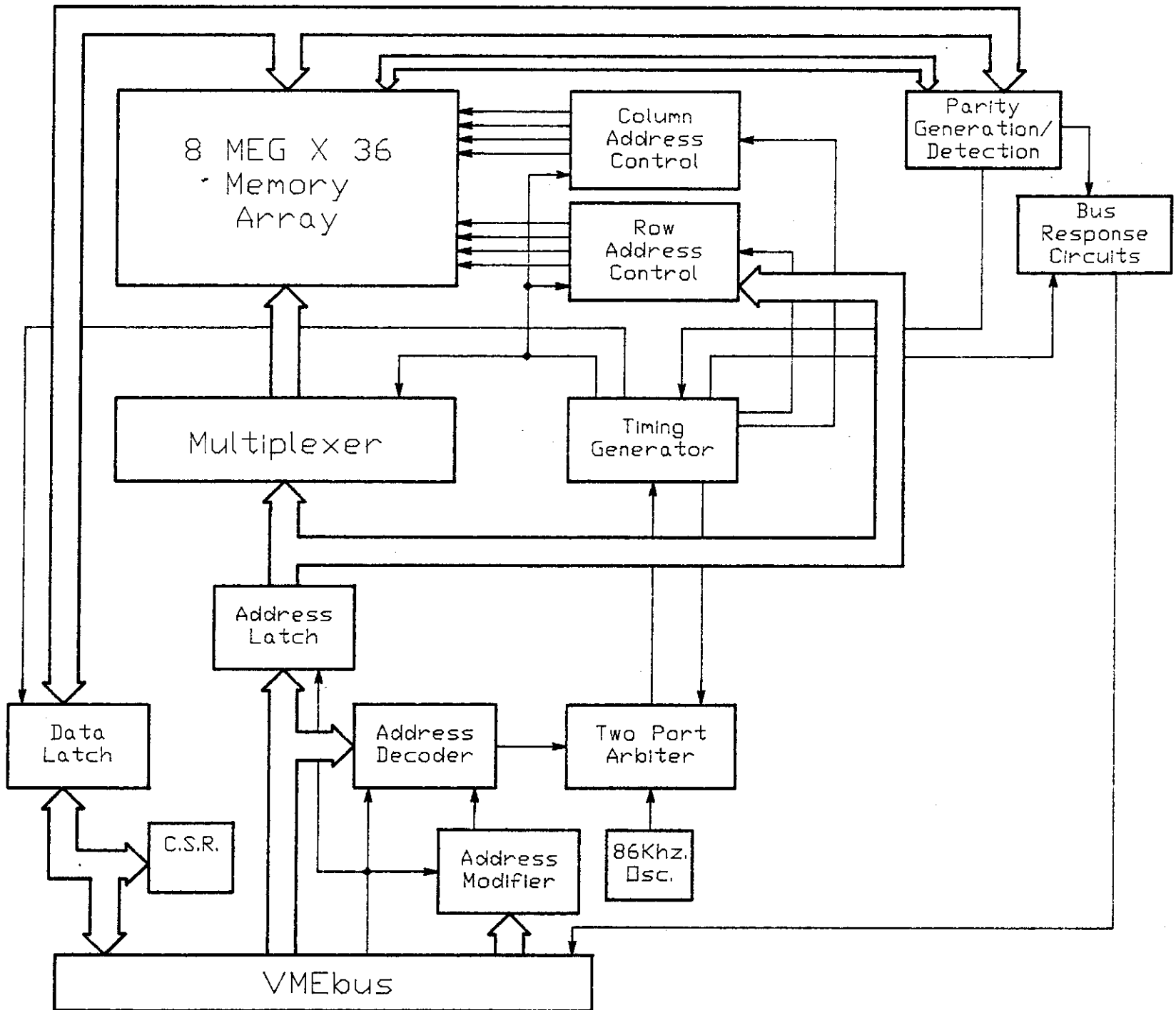
The **MM6260D High Speed Memory** modules are available in several options depending on the capacity required. **Table 1.1** lists the optional part numbers for ordering purposes, the total memory capacity provided by each version.

Table 1.1 Memory Capacity Options

Table 1.1 summarizes the options with respect to storage capacity, available to **MM6260D High Speed Memory** user.

Option	Capacity
MM6260D/8M	8.0M Bytes
MM6260D/12M	12.0M Bytes
MM6260D/16M	16.0M Bytes
MM6260D/24M	24.0M Bytes
MM6260D/28M	28.0M Bytes
MM6260D/32M	32.0M Bytes

Memory capacities above 16 megabytes are provided by an attached mezzanine board.



Revised May 1989

Functional Block Diagram Figure 1.1

1.2.2 OPERATIONAL FEATURES

The **MM6260D High Speed Memory** module contains its own address register and data buffers for total compatibility with the **VMEbus Specification (Rev. C.1)**.

Module selection for the **MM6260D** resides on any 1 Mbyte (100000 hex) boundary (**A24/A32**). The starting and ending addresses of the **MM6260** may be set on any 1 Mbyte boundary within the 4 gigabytes of physical address space, for A32 address modifiers, and on any 1 Mbyte boundary within the 16 megabytes of A24 address space. The A24 ending address is separately selectable so that a portion of the **MM6260** may be mapped into the A24 space, for boards which are required to respond to both A24 and A32 address modifiers on the **VMEbus**.

The **MM6260D High Speed Memory** array can be addressed as 8 bit bytes, 16 bit words, or as 32 bit longwords, using conventional Read/Write, Read/Modify/Write (**RMW**), or **HIGH Performance BLOCK Transfers (BLT)**. Unaligned read or write transfers are also supported.

The **MM6260D** features **RAM Cache**, which provides for improved access and cycle times for accesses in the same 4 Kbyte block of memory as the previous access. Memory cycle and Read/Write access times are shown in table 1.3.

The **MM6260D High Speed Memory** responds to various Address Modifier Codes. These include \$09, \$0A, \$0B, \$0D, \$0E, \$0F and \$17 for A32 accesses; \$29 and \$2D for CSR accesses; \$39, \$3A, \$3B, \$3D, \$3E, \$3F and \$10 for A24 accesses. The codes are decoded by U1 (a socketed IFL). Note that the codes \$17 and \$10 are special (user defined) address modifiers for long block transfers. Various combinations are available to the user (see Section II, jumpers).

The user may select to create his/her own Address Modifier code(s), in this event the Address Modifier evaluation IFL (U1) can be replaced to accommodate the systems' requirements (see Section II, jumpers).

A **Control Status Register (CSR)** is available to allow various dynamic options to be utilized by the software programmer. Included in the **CSR** is a bit to enable the **MM6260D High Speed Memory** to respond to parity error by asserting **BERR*** instead of **DTACK***. Another bit allows wrong parity to be written to the array, to test the parity circuitry. A third bit may be read or written to give the parity error status since the last write to this bit or the last bus reset. A jumper option allows write wrong parity to be disabled always, and **BERR*** to be returned on a parity error always. This eliminates the need for the software to manage the CSR. The **CSR** is an **A16** Slave and has separate address selection jumpers, and may be addressed on any 2 byte boundary in the **VMEbus** I/O address space. Valid data is only driven on the odd byte of this two byte location. (See Section III for programming details).

1.3 GENERAL SPECIFICATIONS

**Table 1.3
General Specifications
MM6260D High Speed Ram Memory Module**

Characteristics	Specifications
Capacity	8M, 12M, 16M, 24M, 28M, or 32M bytes
Address	32 bits A32/A24/BLT/UAT VMEbus
Data In/Data Out	8/16/24/32 bits bidirectional with three-state output D08/D16/D32
Modes of Operation	Read, Write, Read/Modify/Write (RMW), Block Transfers (BLT), Un-aligned (UAT)
Address Modifiers	6 bits, jumper selectable, or user programmable IFL
Error Detetion	Even Parity, one parity bit generated/checked for each byte.
Module Selection VMEbus	Memory selected on 1 Megabyte (\$100000) boundary within the 4G byte address space, for A32 address modifiers; and any 1 Megabyte (\$100000) boundary within the 16M byte address space for A24 address modifiers.
Control Status Register Selection	CSR Selected on any 2 byte boundary in the VMEbus 'A16' I/O Address space.
Interface: Inputs	TTL-compatible
Outputs	48ma. Three-state, TTL-compatible
Operating Temperature	0 to 60 degrees C
Storage Temperature	-40 to +85 degrees C
Relative Humidity	95% without condensation
Power Requirements: +5V (fully-populated)	Standby Operate 3.9A 6.8A

Table 1.3
(continued)

Timing Specifications for the MM6260D Dynamic Ram Memory Module

Cycle Type	Cycle Time	Access Time
Write (RAM Cache hit)	110 nsec.	70 nsec.
Write (RAM Cache miss)	250 nsec.	210 nsec.
Write (Block Transfer)	90 nsec.	60 nsec.
Write (First Cycle of Block Transfer)	170 nsec.	130 nsec.
Read (RAM Cache hit)	150 nsec.	120 nsec.
Read (RAM Cache miss)	290 nsec.	250 nsec.
Read (Block Transfer)	110 nsec.	80 nsec.
Read (First Cycle of Block Transfer)	210 nsec.	180 nsec.

Table 1.3
P1 Connector VMEbus Pin Assignments

PAGE NUMBER	ROWa SIGNAL MNEMONIC	ROWb SIGNAL MNEMONIC	ROWc SIGNAL MNEMONIC
1	D00	** BBSY*	D08
2	D01	** BCLR*	D09
3	D02	** ACFAIL*	D10
4	D03	BG0IN*	D11
5	D04	BG0OUT*	D12
6	D05	BG1IN*	D13
7	D06	BG1OUT*	D14
8	D07	BG2IN*	D15
9	GND	BG2OUT*	GND
10	** SYSCLK	BG3IN*	** SYSFAIL*
11	GND	BG3OUT*	BERR*
12	DS1*	BR0*	SYSRESET*
13	DS0*	BR1*	LWORD*
14	WRITE*	BR2*	AM5
15	GND	BR3*	A23
16	DTACK*	AM0	A22
17	GND	AM1	A21
18	AS*	AM2	A20
19	GND	AM3	A19
20	IACK*	GND	A18
21	IACKIN*	** SERCLK(1)	A17
22	IACKOUT*	** SERDAT*(1)	A16
23	AM4	GND	A15
24	A07	** IRQ7*	A14
25	A06	** IRQ6*	A13
26	A05	** IRQ5*	A12
27	A04	** IRQ4*	A11
28	A03	** IRQ3*	A10
29	A02	** IRQ2*	A09
30	A01	** IRQ1*	A08
31	** -12v	** +5vSTDBY	** +12v
32	+5v	+5v	+5v

** - No Connection on MM6260D High Speed Memory

Table 1.4
P2 Connector VMEbus Pin Assignments

PAGE NUMBER	ROWa SIGNAL MNEMONIC	ROWb SIGNAL MNEMONIC	ROWc SIGNAL MNEMONIC
1	N/C	+5v	N/C
2	N/C	GND	N/C
3	N/C	** RESERVED	N/C
4	N/C	A24	N/C
5	N/C	A25	N/C
6	N/C	A26	N/C
7	N/C	A27	N/C
8	N/C	A28	N/C
9	N/C	A29	N/C
10	N/C	A30	N/C
11	N/C	A31	N/C
12	N/C	GND	N/C
13	N/C	+5v	N/C
14	N/C	D16	N/C
15	N/C	D17	N/C
16	N/C	D18	N/C
17	N/C	D19	N/C
18	N/C	D20	N/C
19	N/C	D21	N/C
20	N/C	D22	N/C
21	N/C	D23	N/C
22	N/C	GND	N/C
23	N/C	D24	N/C
24	N/C	D25	N/C
25	N/C	D26	N/C
26	N/C	D27	N/C
27	N/C	D28	N/C
28	N/C	D29	N/C
29	N/C	D30	N/C
30	N/C	D31	N/C
31	N/C	GND	N/C
32	N/C	+5v	N/C

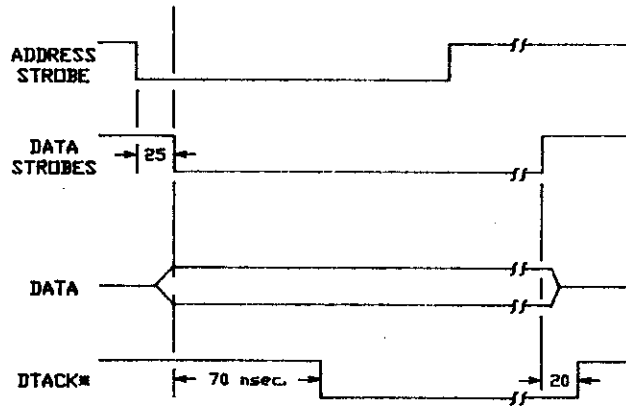
** - No Connection on MM6260D VMEbus Memory

1.4 INTERFACE TIMING

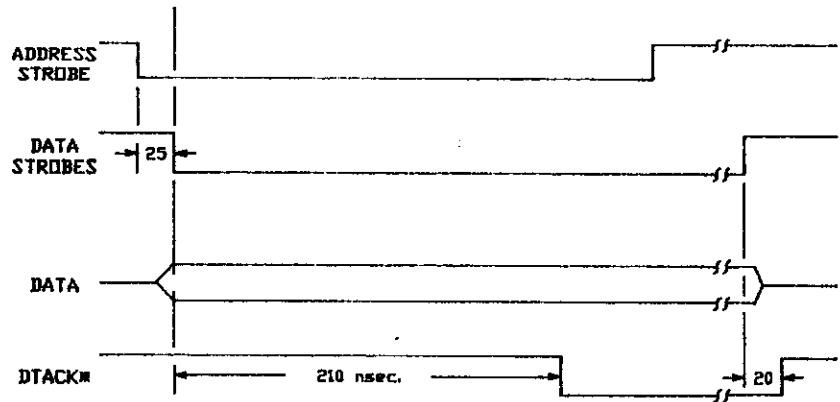
The **VMEbus** Interface Timing Diagrams (Figures 1.2-1.4), illustrates the timing relationships on the Data Transfer bus, for Write, and Read Cycles. Access delay time is measured from the leading edge of the Data strobes.

The refresh cycle timing is the same as read cycles. Refresh cycles are repeated once every 10usec. The cycle interval timing is generated by a free running oscillator (U64) providing a refresh transparent to memory access cycles.

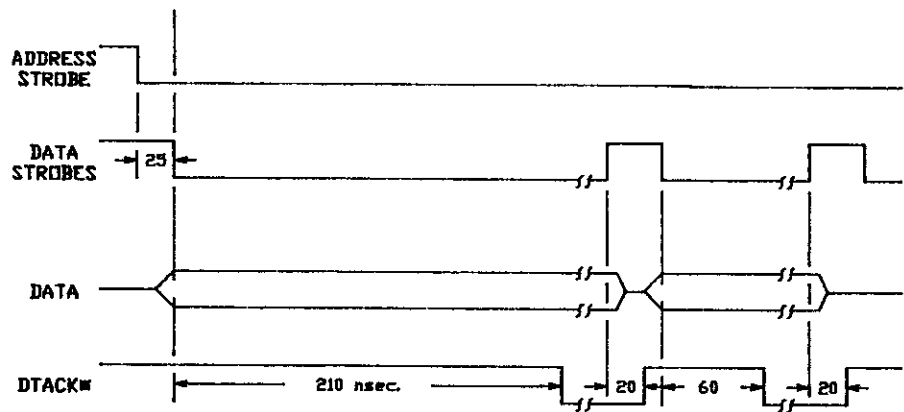
CACHE-HIT WRITE CYCLE



CACHE-MISS WRITE CYCLE

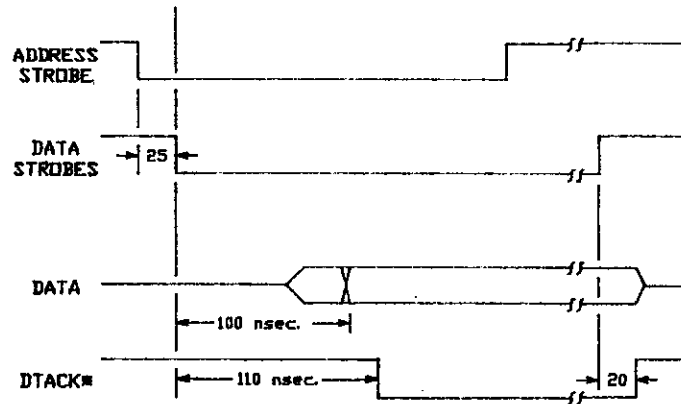


BLOCK MODE WRITE CYCLES

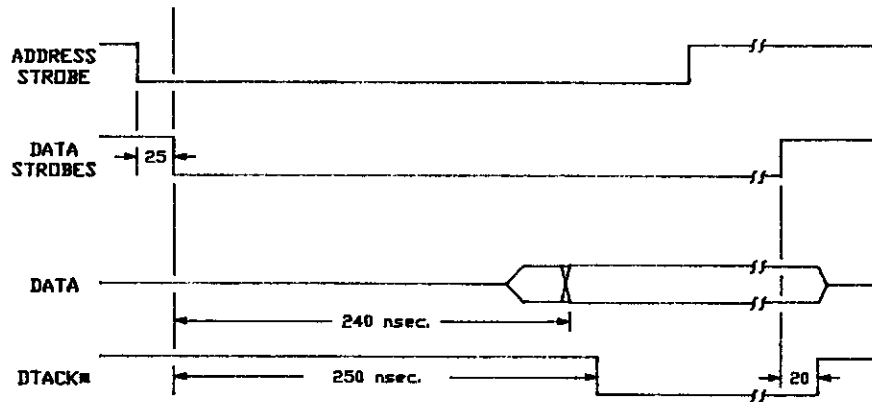


VMEbus Write Timing Diagram Figure 1.2

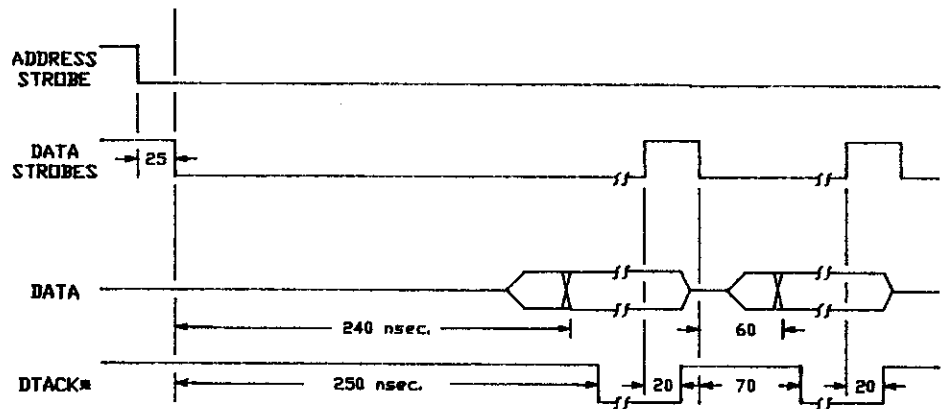
CACHE-HIT READ CYCLE



CACHE-MISS READ CYCLE



BLOCK MODE READ CYCLES



VMEbus Read Timing Diagram Figure 1.4

1.5 MEMORY ARRAY ORGANIZATION

The memory array is partitioned into eight 1024K x 36 bit segments. The minimum memory configuration would be 1024K x 36 bits, including the four parity bit DRAMs in segment zero. This would translate to 4 Megabytes minimum configuration for the **MM6260D Memory**.

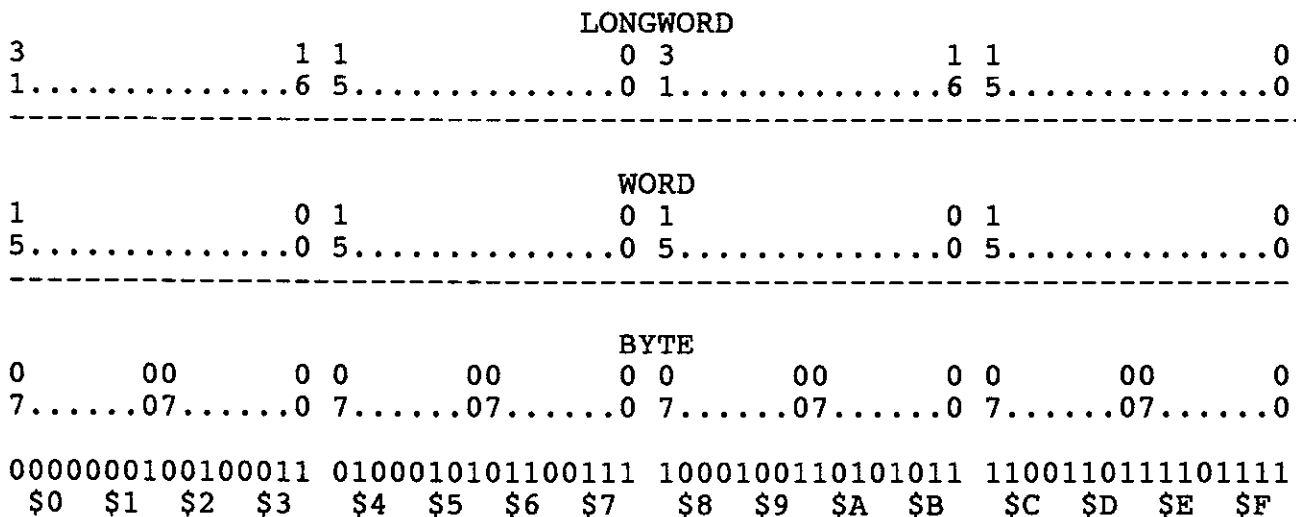
Although the **MM6260D Memory** is partitioned as four blocks of 36 bits each (32 plus 4 parity), the system will only see 32 bits of data during memory references, since the parity bits are generated or checked transparent to the user. The 32 bits of data are divided into 4 bytes (8 bits each). Memory reads and writes may be 8, 16, 24 or 32 bits wide.

Determining which bits constitute what byte may be somewhat confusing. This can be cleared up by seeing the same data in the various formats used in most systems (IE: Byte, Word, and Longword). If the contents of the first 8 locations in memory are \$01 \$23 \$45 \$67 \$89 \$AB \$CD \$EF they would be seen in various formats as shown below.

Memory Array Organization Figure 1.4

BYTE Format		WORD Format		LONGWORD Format	
Location	Data	Location	Data	Location	Data
\$00000000	\$01	\$00000000	\$0123	\$00000000	\$01234567
\$00000001	\$23	\$00000002	\$4567	\$00000004	\$89ABCDEF
\$00000002	\$45	\$00000004	\$89AB		
\$00000003	\$67	\$00000006	\$CDEF		
\$00000004	\$89				
\$00000005	\$AB				
\$00000006	\$CD				
\$00000007	\$EF				

BIT Organizations



SECTION II

INSTALLATION

2.1 INTRODUCTION

This section details a step by step procedure to interface the **MM6260D Memory** to the **VMEbus**.

2.2 UNPACKING INSTRUCTIONS

Unpack module from shipping carton. If carton is damaged upon receipt, request that the carrier's agent be present during unpacking and inspection of the equipment. Refer to packing list and verify that all items are present. Save packing material for storing or reshipping the equipment. For repairs or replacement of a board damaged during shipment, contact **MICRO MEMORY, Inc.** to obtain a Return Authorization number and further instructions.

2.3 HARDWARE PREPARATION

The memory module should be inspected and prepared for jumper placement prior to system installation. The following sections describe the proper jumper options necessary for system operation (see Section 2.5, for jumper options).

2.3.1 Handling Procedure

The **MM6260D High Speed Memory** uses CMOS components that are susceptible to damage if exposed to static electrical charges. To avoid damage of these components during handling, testing or operation, the following procedure should be used.

- A. Device leads should contact conductive material to avoid building of any static charge, except during testing or operation.
- B. Soldering iron tips, metal fixtures, tools, and handling facilities used in preparing the module for operation should be grounded.
- C. Devices should never be removed or inserted while power is applied to the module because voltage transients may permanently damage the devices and/or module.
- D. **The memory module should never be plugged in or out of the cardcage while power is applied.**
- E. External signals should not be applied to device inputs while power is removed.
- F. Any memory module removed from the system should be transferred to either non-conductive foam or an anti-static plastic bag for storage or shipment.

2.4 OPERATING ENVIRONMENT

The **MM6260D High Speed Memory** is an extremely **High Density** memory product. Containing, 64 bits of high current (48ma.) data bus drivers, numerous high speed components. And as a result, the environment into which the **MM6260D Memory** is placed, must be carefully considered.

2.4.1 AIRFLOW AND COOLING

Due to the extremely high component density of the **MM6260D Memory**, **an adequate airflow is required to maintain the** operating temperature within specifications of the memory module. Failure to adhere to these requirements may result in poor long term reliability.

2.4.2 POWER REQUIREMENTS

The power requirements of **MM6260D High Speed Memory** are such, that the module should never be operated while powered only by the **P1** connector. Hence power should be applied to the appropriate pins (See Tables 1.3 & 1.4) of both the **P1** and the **P2** connector prior to operation of the **MM6260D Memory**.

2.5 JUMPER OPTIONS

There are several jumper options attainable on the **MM6260D Memory** module, depending on the user application. All of the available options are selected by installing or removing mini-jumpers on wire-wrap pins on 0.100 inch centers. (see Figure 2.7)

2.5.1 Address Modifier Evaluation/Selection

The **MM6260D High Speed Memory** evaluates the Address Modifiers from the **VMEbus** to determine if they are to be responded to. The **MM6260D Memory** may be configured by jumpers to respond to **EXTENDED A32** address modifier codes (where all 32 bits are decoded for module selection) or to **STANDARD A24** address modifier codes (where only the lower 24 address bits are decoded for module selection), or to both sets of address modifier codes. When jumper **E3** is removed, the module will respond to **A32** address modifier codes, and when jumper **E4** is removed, the module will repond to **A24** address modifier codes. As shipped from the factory, the **MM6260D Memory** E3 removed and E4 installed, causing it to respond to **EXTENDED A32** Address Modifier codes. These Address Modifier codes are described in Appendix A. The user may select to replace the Address Modifier selection **IFL (U1)**, to allow for some other combination or the creation of a special (user defined) code or codes.

2.5.2 Memory Device Size Selection (Factory, 1Mbit)

The **MM6260D High Speed Memory** is designed to accomodate either 1 Mbit DRAMs or (when available) 4Mbit DRAMs. When using 1 Mbit DRAMs, jumpers should be installed between positions 2 and 3 of jumper blocks **E5**, **E6**, and **E7**. Jumper **E8** should be removed. These are the default settings. When using 4 Mbit DRAMs, jumpers should be installed between positions 1 and 2 of jumper blocks **E5**, **E6**, **E7** and **E8**.

2.5.3 Parity Error LED Latch on Error (Factory installed)

The **MM6260D High Speed Memory** has a parity error indicator LED, which will be turned on by a parity error during a read access. If jumper **E2** is installed, it will remain on until a bus reset, or reset by writing a 0 to the **CSR**, bit 7, if the **CSR** is enabled. (see section 2.5.4, below) If jumper **E2** is removed, the LED will be turned off by the next write access or next read access without a parity error. See Section 2.6.4 for **CSR** selection and Section 3.1 for **CSR** bit descriptions.

2.5.4 CSR Enable (Factory, CSR enabled)

If jumper E1 is removed, the CSR is enabled. A bus reset causes all bits in the CSR to be reset. Writing a 1 to bit 0 of the CSR causes a **BERR*** to be generated for any read cycle where a parity error is detected. Writing a 1 to bit 1 causes the wrong parity to be written with the bytes written during any memory write cycles which follow. This allows testing of the parity circuitry. Bits 2 through 6 may be written and read back, but have no effect on the **MM6260 Memory Board**. Bit 7 is set whenever a parity error is detected during a read cycle, regardless of the condition of bit 0. Writing a 0 to bit 7 resets it, and if the CSR is enabled, also resets the parity error LED. If jumper E1 is installed: **BERR*** is always returned for read accesses where a parity error is detected; write wrong parity is inhibited; and the parity error LED may only be reset by a bus reset.

NOTE: See Section 2.6.4 for CSR selection, and Section 3.1 for CSR bit arrangement.

2.6 ADDRESS SWITCH SETTINGS

The **MM6260D High Speed Memory** contains seven (7) major switches that must be configured prior to installation before proper operation can be obtained. (See Figure 2.7 for switch locations) These are SW1 through SW7. A closed switch position represents a 0, and an open switch position represents a 1.

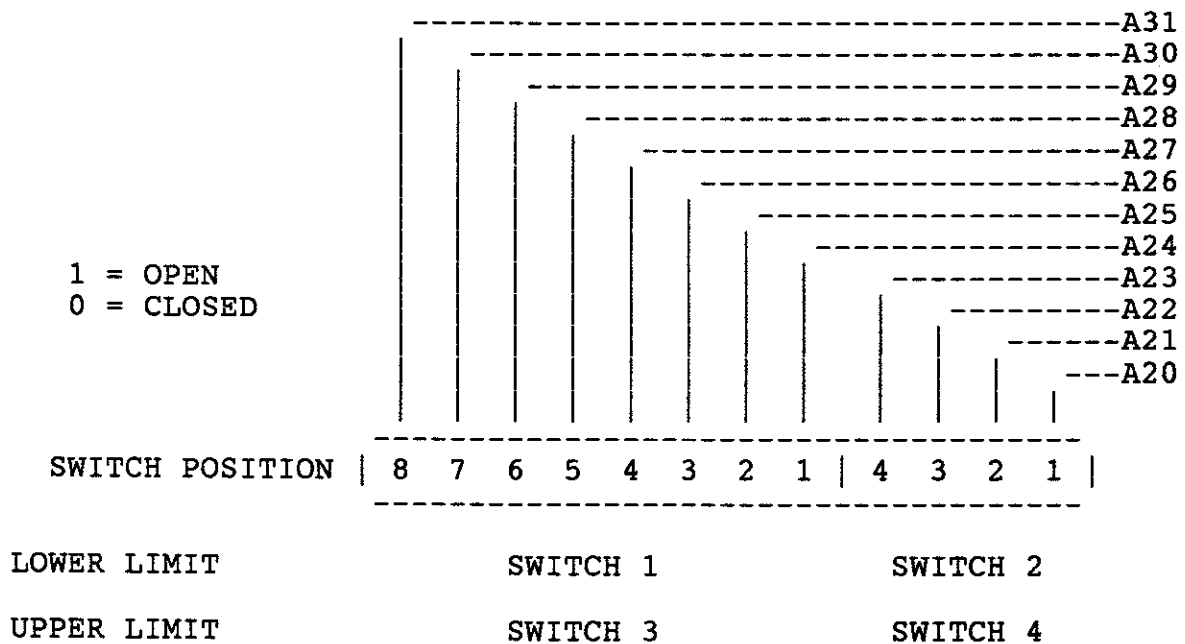
2.6.1 VMEbus Module Selection

Module selection for the **MM6260D Memory** resides on 1024K (\$100000) byte boundaries. Selection of the **VMEbus** lower limit and upper limit on a particular 1024 kilobyte (\$100000) boundary within the selected bank is accomplished by closing or opening the appropriate switch positions in switches 1 through 5.

2.6.1.1 Address Selection for A32 Accesses

For A32 address modifiers, the starting address is set by the twelve bits of switches 1 and 2. Position 8 of switch 1 is the most significant bit, and corresponds to A31; position 1 of switch 2 is the least significant bit, and corresponds to A20. The ending address is set by the twelve bits of switches 3 and 4; position 8 of switch 3 is the most significant bit and corresponds to A31; position 1 of switch 4 is the most significant bit, and corresponds to A20. On all switch positions, an open corresponds to a 1, while a closed position corresponds to a 0.

Figure 2.1 Upper & Lower Address selection for A32 Address Modifiers

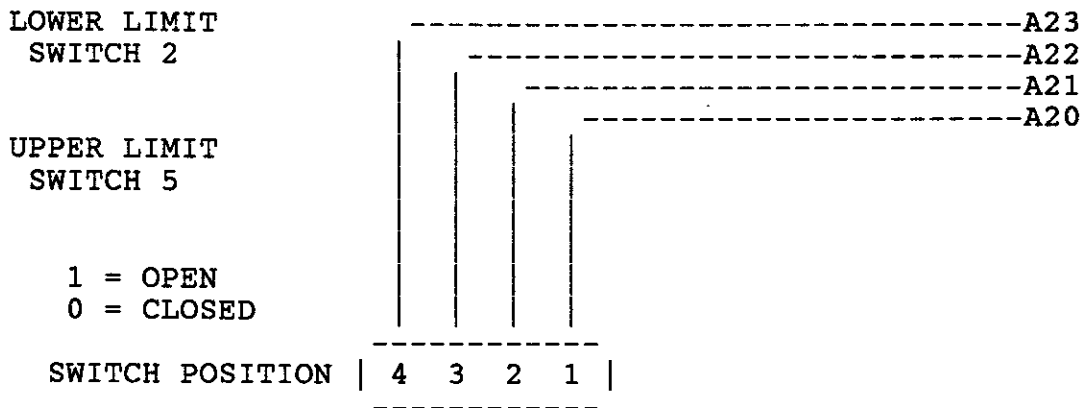


The above address switch arrangement can be thought of as three hex digits for the starting address, with the most significant digit being switch 1, positions 8-5; the next most significant digit being switch 1, positions 4-1; and the least significant digit being switch 2, positions 4-1. The three hex digits for the ending address are: the most significant digit is switch 3, positions 8-5; the next most significant digit is witch 3, positions 4-1; and the least significant digit is switch 4, positions 4-1.

2.6.1.2 Address Selection for A24 Accesses

For A24 address modifiers, the starting address is set by the same four bits of switch 2 which form the lower four bits of the A32 starting address. Position 4 is the most significant bit, and corresponds to A23; position 1 is the least significant bit, and corresponds to A20. In order to accomodate some processors which have on-board memory in the upper portion of the A24 address space, the ending address for A24 accesses is set by a separate switch from the A32 ending address. Switch 5 sets the A24 ending address. Position 4 is the most significant bit, and corresponds to A23. Position 1 is the least significant bit, and corresponds to A20.

Figure 2.2 Upper & Lower Address selection for A24 Address Modifiers



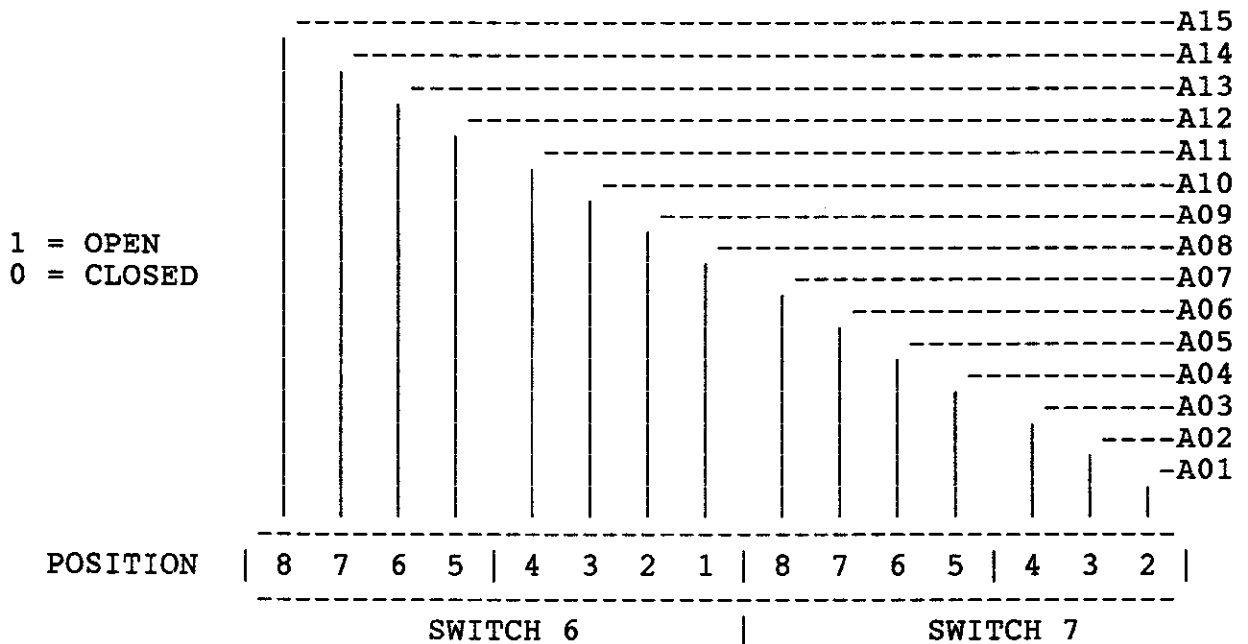
This may be thought of as a single hex digit for the starting address, which is switch 2, positions 4-1; and a single hex digit for the ending address, which is switch 5, positions 4-1.

The fact that the ending address for A24 accesses is separate from the ending address for A32 accesses allows A24 and A32 bus masters to access a common portion of memory of the MM6260 memory. For example, if an A24 disk controller, and an A32 processor were accessing an MM6260, where the starting address was \$00800000; the A24 ending address was \$FFFFFF; and the A32 ending address was \$01800000, then both masters could access the first eight Mbytes of the memory, but only the processor could access the last eight Mbytes of the memory.

2.6.4 Control / Status Register Address Selection

Selection of the **CSR** address may be on any **2 byte** boundary, (ie: \$0000, \$0002, ..., \$FFFE), within the **VMEbus** I/O space, by closing or opening the appropriate positions on switches 6 and 7. Switch 6, position 8 corresponds to A15, and position 1 corresponds to A08. Switch 7, position 8 corresponds to A07, and position 2 to A01. This arrangement could be viewed as four hex digits.

Figure 2.3 Control / Status Register Address selection



2.6.5 Example Addressing

To address the **MM6260D High Speed Memory**, the user must determine first where the **MM6260D Memory** is to be located. In this example I have chosen from 00100000 to \$010FFFFFF for the **VMEbus A32** accesses and from \$100000 to \$EFFFFFF for the **VMEbus A24** accesses. And an address of \$0404 (**VMEbus I/O space**) for the **CSR**.

Figure 2.4 Example of VMEbus address selection:

LOWER LIMIT	SWITCH 1	SWITCH 2	
	8	1 4	1

SWITCH POSITION	0 0 0 0 0 0 0 0	0 0 0 1	
1 = OPEN	-----		
0 = CLOSED			
UPPER LIMIT (A32 access)	SWITCH 3	SWITCH 4	
	8	1 4	1

SWITCH POSITION	0 0 0 0 0 0 0 1	0 0 0 0	

UPPER LIMIT (A24 access)	SWITCH 5		
	4	1	

SWITCH POSITION	1 1 1 0		

Figure 2.5 Example of CSR addressing

	SWITCH 6	
	8	1

	0 0 0 0	0 1 0 0

	\$0XXX	\$X4XX
	SWITCH 7	
	8	2

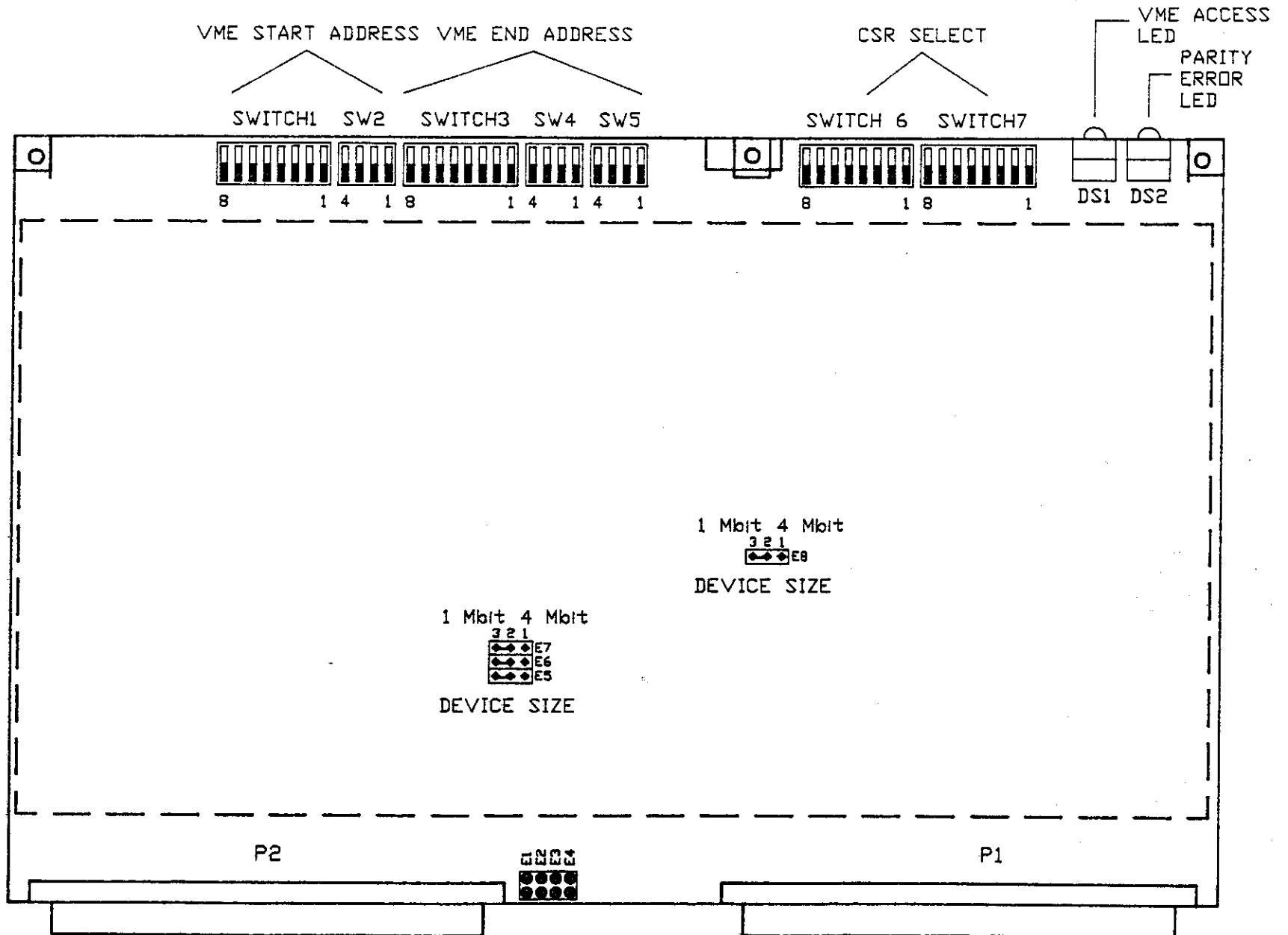
	0 0 0 0	0 1 0

	\$XX0X	\$XXX4

Then the **CSR** would be selected at (\$0404).

2.7 Installation in the system

After selecting the memory for the proper address locations by setting the appropriate switches (see Section 2.6), installing/removing the user defined option jumpers (see Section 2.5), and after following the guidelines set forth in Section 2.3; remove power, install the **MM6260D High Speed Memory** into the system, reapply power to the system.



Revised May 1989
 Jumper and Indicator Locations Figure 2.6
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SECTION III

PROGRAMMING INFORMATION

3.1 Control Status Register

The **Control Status Register (CSR)** provides a **VMEbus** accessible register to control and determine the status of the **MM6260D High Speed Memory**. In the following sections, the CSR bits are defined and their use is explained.

Table 3.1 C.S.R. Bit Definitions

ODD BYTE

7	6	5	4	3	2	1	0	
								-- (EPERR) Enable Parity Error Reporting
								---- (WWP) Write Wrong Parity
								----- Not used
								----- Not used
								----- Not used
								----- Not used
								----- Not used
								----- (PE) Parity Error

Note: The even byte, if read, will return all 1's.

3.1.1 Parity Error Detection

The **MM6260D High Speed Memory** generates even parity for each byte written during a write access; and checks even parity for each byte read during a read access. If a parity error is detected during a read access, the **CSR PE** bit will be set. It will be reset by a system bus reset, and may also be reset by writing a 0 to bit 7 of the CSR. If bit 0 is set, (**EPERR**), and a parity error is detected during a **VMEbus** read access, the **BERR*** lead is asserted instead of the **DTACK*** lead. **EPERR** will be reset by a system bus reset, and may also be reset by writing a 0 to bit 0 of the CSR.

3.1.2 Write Wrong Parity

When bit 1 of the **CSR** is set, the parity circuitry may be tested by causing the wrong parity bits to be generated, and written for all locations written while this bit is set.

3.2 Initialization of Memory

Since the memory will power up with random data, each byte location should be written to initialize its associated parity bit, before it is read, or before **EPERR** in the CSR is set to enable ***BERR** to be asserted for parity errors on read accesses.

```

@DEVICE TYPE
PLUS153
@DRAWING
      MM6232B
@REVISION
      V1.1
@DATE
      May 8, 1989 [11:05am]
@SYMBOL
@COMPANY
      MICRO MEMORY
@NAME
      ROGER PEEBLES
@DESCRIPTION
      VME ADDRESS MODIFIER DECODE
@COMMON PRODUCT TERM
@I/O DIRECTION
@LOGIC EQUATION

"Extended supervisor block xfer"
AM32 = /AM5 * /AM4 * AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
"Extended supervisory Program access"
      + /AM5 * /AM4 * AM3 * AM2 * AM1 * /AM0 * /IACK * /RESET
"Extended supervisory data access"
      + /AM5 * /AM4 * AM3 * AM2 * /AM1 * AM0 * /IACK * /RESET
"Extended non-privileged block xfer"
      + /AM5 * /AM4 * AM3 * /AM2 * AM1 * AM0 * /IACK * /RESET
"Extended non-privileged program access"
      + /AM5 * /AM4 * AM3 * /AM2 * AM1 * /AM0 * /IACK * /RESET
"Extended non-privileged data access"
      + /AM5 * /AM4 * AM3 * /AM2 * /AM1 * AM0 * /IACK * /RESET
"Special long block xfer"
      + /AM5 * AM4 * /AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
      ;

"Standard supervisor block xfer"
AM24 = AM5 * AM4 * AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
"Standard supervisory Program access"
      + AM5 * AM4 * AM3 * AM2 * AM1 * /AM0 * /IACK * /RESET
"Standard supervisory data access"
      + AM5 * AM4 * AM3 * AM2 * /AM1 * AM0 * /IACK * /RESET
"Standard non-privileged block xfer"
      + AM5 * AM4 * AM3 * /AM2 * AM1 * AM0 * /IACK * /RESET
"Standard non-privileged program access"
      + AM5 * AM4 * AM3 * /AM2 * AM1 * /AM0 * /IACK * /RESET
"Standard non-privileged data access"
      + AM5 * AM4 * AM3 * /AM2 * /AM1 * AM0 * /IACK * /RESET
"Special long block xfer"
      + /AM5 * AM4 * /AM3 * /AM2 * /AM1 * /AM0 * /IACK * /RESET
      ;

```

```
"Short supervisory access"
AM16 = AM5 * /AM4 * AM3 * AM2 * /AM1 * AM0 * /IACK * /RESET
"Short non-privileged access"
  + AM5 * /AM4 * AM3 * /AM2 * /AM1 * AM0 * /IACK * /RESET
  ;

"Extended supervisor block xfer"
VMEBLK = /AM5 * /AM4 * AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
"Standard supervisor block xfer"
  + AM5 * AM4 * AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
  ;

"Special long block xfer"
SPBLK = /AM5 * AM4 * /AM3 * AM2 * AM1 * AM0 * /IACK * /RESET
  + /AM5 * AM4 * /AM3 * /AM2 * /AM1 * /AM0 * /IACK * /RESET
  ;
```



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